

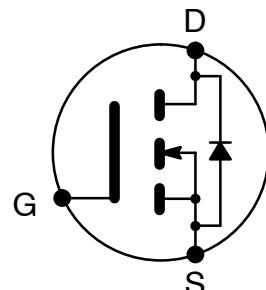


ELECTRONICS, INC.  
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**NTE2376  
MOSFET  
N-Ch, Enhancement Mode  
High Speed Switch  
TO247 Type Package**

**Features:**

- Dynamic dv/dt Rating
- Repetitive Avalanche Rated
- Isolated Central Mounting Hole
- Fast Switching
- Ease of Parallelizing
- Simple Drive Requirements



**Absolute Maximum Ratings:**

Continuous Drain Current ( $V_{GS} = 10V$ ),  $I_D$

$T_C = +25^\circ C$ .....	30A
$T_C = +100^\circ C$ .....	19A

Pulsed Drain Current (Note 1),  $I_{DM}$  ..... 120A

Power Dissipation ( $T_C = +25^\circ C$ ),  $P_D$  ..... 190W  
Derate Linearly Above  $25^\circ C$  .....  $1.5W/^\circ C$

Gate-to-Source Voltage,  $V_{GS}$  .....  $\pm 20V$

Single Pulse Avalanche Energy (Note 2),  $E_{AS}$  ..... 410mJ

Avalanche Current (Note 1),  $I_{AR}$  ..... 30A

Repetitive Avalanche Energy (Note 1),  $E_{AR}$  ..... 19mJ

Peak Diode Recovery dv/dt (Note 3), dv/dt ..... 5V/ns

Operating Junction Temperature Range,  $T_J$  .....  $-55^\circ$  to  $+150^\circ C$

Storage Temperature Range,  $T_{stg}$  .....  $-55^\circ$  to  $+150^\circ C$

Lead Temperature (During Soldering, 1.6mm from case for 10sec),  $T_L$  .....  $+300^\circ C$

Mounting Torque (6-32 or M3 Screw) ..... 10 lbf/in (1.1 N•m)

Thermal Resistance, Junction-to-Case,  $R_{thJC}$  .....  $0.65^\circ C/W$

Thermal Resistance, Junction-to-Ambient,  $R_{thJA}$  .....  $40^\circ C/W$

Typical Thermal Resistance, Case-to-Sink (Flat, Greased Surface),  $R_{thCS}$  .....  $0.24^\circ C/W$

Note 1. Repetitive rating; pulse width limited by maximum junction temperature.

Note 2.  $V_{DD} = 50V$ , starting  $T_J = +25^\circ C$ ,  $L = 683\mu H$ ,  $R_G = 25\Omega$ ,  $I_{AS} = 30A$

Note 3.  $I_{SD} \leq 30A$ ,  $di/dt \leq 190A/\mu s$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  $T_J \leq +150^\circ C$

**Electrical Characteristics:** ( $T_J = +25^\circ\text{C}$  unless otherwise specified)

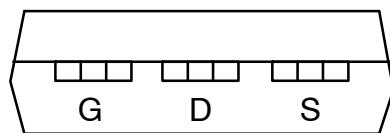
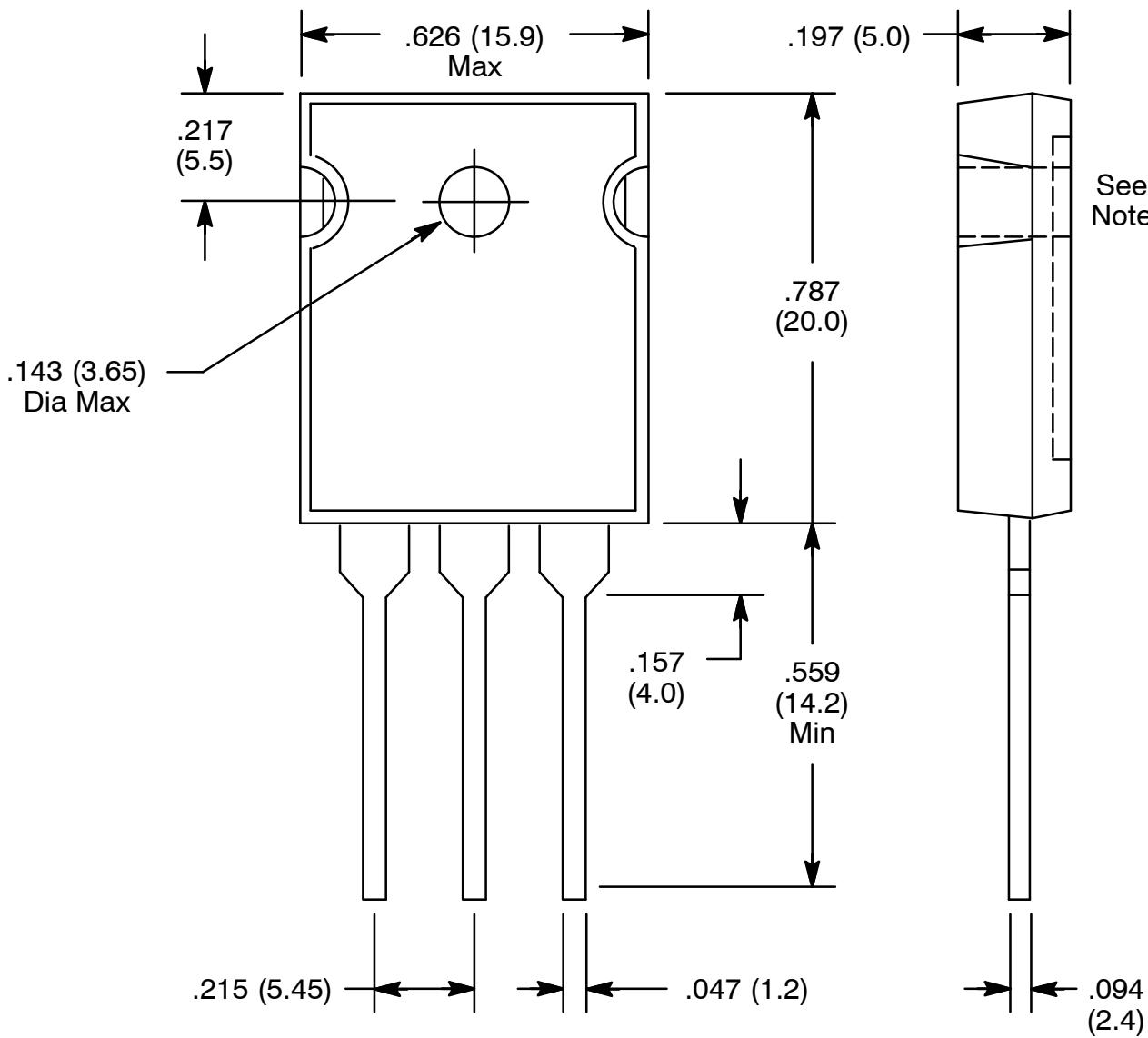
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}$ , $I_D = 250\text{mA}$	200	—	—	V
Breakdown Voltage Temp. Coefficient	$\frac{V_{(\text{BR})\text{DSS}}}{T_J}$	Reference to $+25^\circ\text{C}$ , $I_D = 1\text{mA}$	—	0.27	—	$\text{V}/^\circ\text{C}$
Static Drain-to-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}$ , $I_D = 18\text{A}$ , Note 4	—	—	0.085	$\pm$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}$ , $I_D = 250\text{mA}$	2.0	—	4.0	V
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}} = 50\text{V}$ , $I_D = 18\text{A}$ , Note 4	12	—	—	mhos
Drain-to-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 200\text{V}$ , $V_{\text{GS}} = 0\text{V}$	—	—	25	$\leq\text{A}$
		$V_{\text{DS}} = 160\text{V}$ , $V_{\text{GS}} = 0\text{V}$ , $T_J = +125^\circ\text{C}$	—	—	250	$\leq\text{A}$
Gate-to-Source Forward Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = 20\text{V}$	—	—	100	nA
Gate-to-Source Reverse Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = -20\text{V}$	—	—	-100	nA
Total Gate Charge	$Q_g$	$I_D = 30\text{A}$ , $V_{\text{DS}} = 160\text{V}$ , $V_{\text{GS}} = 10\text{V}$ , Note 4	—	—	140	nC
Gate-to-Source Charge	$Q_{\text{gs}}$		—	—	28	nC
Gate-to-Drain ("Miller") Charge	$Q_{\text{gd}}$		—	—	74	nC
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 100\text{V}$ , $I_D = 30\text{A}$ , $R_G = 6.2\pm$ , $R_D = 3.2\pm$ , Note 4	—	16	—	ns
Rise Time	$t_r$		—	86	—	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		—	70	—	ns
Fall Time	$t_f$		—	62	—	ns
Internal Drain Inductance	$L_D$	Between lead, .250in. (6.0) mm from package and center of die contact	—	5.0	—	nH
Internal Source Inductance	$L_S$		—	13.0	—	nH
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}$ , $V_{\text{DS}} = 25\text{V}$ , $f = 1\text{MHz}$	—	2800	—	pF
Output Capacitance	$C_{\text{oss}}$		—	780	—	pF
Reverse Transfer Capacitance	$C_{\text{rss}}$		—	250	—	pF

**Source-Drain Ratings and Characteristics:**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Continuous Source Current (Body Diode)	$I_S$		—	—	30	A
Pulsed Source Current (Body Diode)	$I_{\text{SM}}$	Note 1	—	—	120	A
Diode Forward Voltage	$V_{\text{SD}}$	$T_J = +25^\circ\text{C}$ , $I_S = 30\text{A}$ , $V_{\text{GS}} = 0\text{V}$ , Note 4	—	—	2.0	V
Reverse Recovery Time	$t_{\text{rr}}$	$T_J = +25^\circ\text{C}$ , $I_F = 30\text{A}$ , $di/dt = 100\text{A}/\text{s}$ , Note 4	—	360	540	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		—	4.6	6.9	$\leq\text{C}$
Forward Turn-On Time	$t_{\text{on}}$	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S+L_D$ )				

Note 1. Repetitive rating; pulse width limited by maximum junction temperature.

Note 4. Pulse width  $\leq 300\text{s}$ ; duty cycle  $\leq 2\%$ .



TO247

**Note:** Drain connected to metal part of mounting surface.

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